



Material Content Data Sheet



Sales Product Name		IPB019N08N3 G		Issued		25. January 2018		
MA#		MA000987348						
Package		PG-TO263-7-3		Weight*		1529.04 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.294	0.80	0.80	8040	8040
leadframe	inorganic material	phosphorus	7723-14-0	0.241	0.02		158	
	non noble metal	iron	7439-89-6	0.803	0.05		525	
	non noble metal	copper	7440-50-8	801.714	52.43	52.50	524324	525007
	non noble metal	aluminium	7429-90-5	14.673	0.96	0.96	9596	9596
wire	non noble metal	aluminium	7429-90-5	14.673	0.96	0.96	9596	9596
encapsulation	organic material	carbon black	1333-86-4	8.590	0.56		5618	
	plastics	epoxy resin	-	94.493	6.18		61799	
	inorganic material	silicondioxide	60676-86-0	469.600	30.71	37.45	307121	374538
leadfinish	non noble metal	tin	7440-31-5	12.317	0.81	0.81	8055	8055
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.269	0.02	0.02	176	177
solder	non noble metal	tin	7440-31-5	0.154	0.01		101	
	noble metal	silver	7440-22-4	0.192	0.01		126	
	non noble metal	lead	7439-92-1	7.350	0.48	0.50	4807	5034
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	iron	7439-89-6	0.106	0.01		70	
	non noble metal	copper	7440-50-8	106.210	6.95	6.96	69462	69553
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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